2SA2079

Silicon PNP epitaxial planar type

For general amplification Complementary to 2SC5848

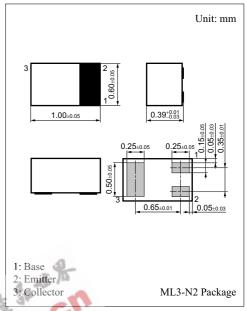
■ Features

- High forward current transfer ratio h_{FE}
- Suitable for high-density mounting and douwsizing of the equipment for ultraminiature leadless package

Package: 0.6 mm × 1.0 mm (hight 0.39 mm)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-45	V	
Collector-emitter voltage (Base open)	V _{CEO}	-45	V	
Emitter-base voltage (Collector open)	V _{EBO}	-7	V	
Collector current	$I_{\rm C}$	-100	mA	
Peak collector current	I _{CP}	-200	mA	
Collector power dissipation	P _C	100	mW	
Junction temperature	T _j	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	



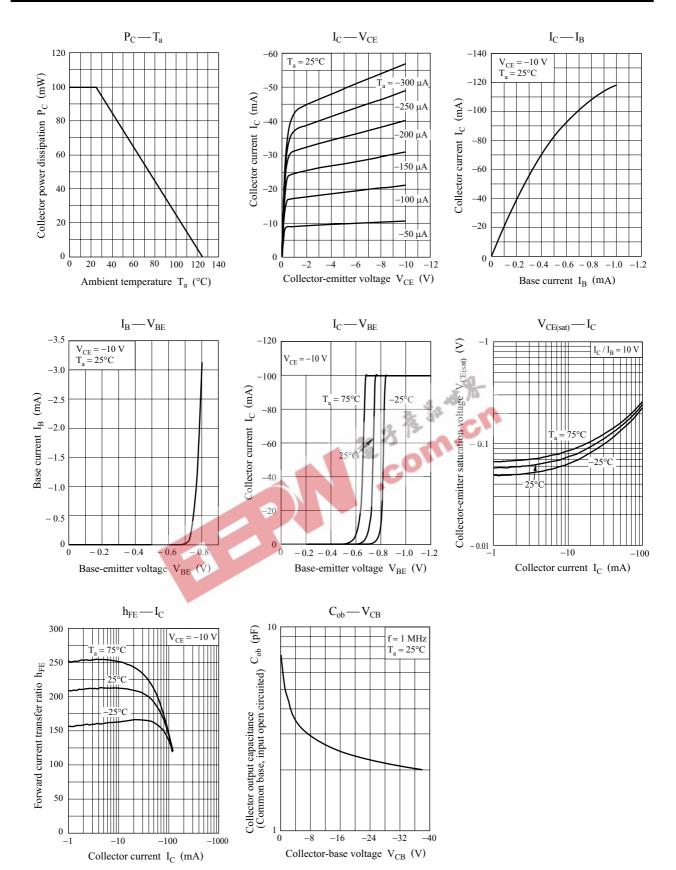
Marking Symbol: 3D

■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_{\rm C} = -10 \mu\text{A}, I_{\rm E} = 0$	-45			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-45			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10 \mu\text{A}, I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{\rm CB} = -20 \text{ V}, I_{\rm E} = 0$			-0.1	μΑ
Collector-emitter cut-off current (Base open)	I_{CEO}	$V_{CE} = -10 \text{ V}, I_{B} = 0$			-100	μΑ
Forward current transfer ratio	h_{FE}	$V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$	180		390	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -100 \text{ mA}, I_B = -10 \text{ mA}$		-0.2	-0.5	V
Transition frequency	f_T	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		2.2		pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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